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ADN4612ACPZ Package Nominal dimension change from 0.80 to 0.85mm

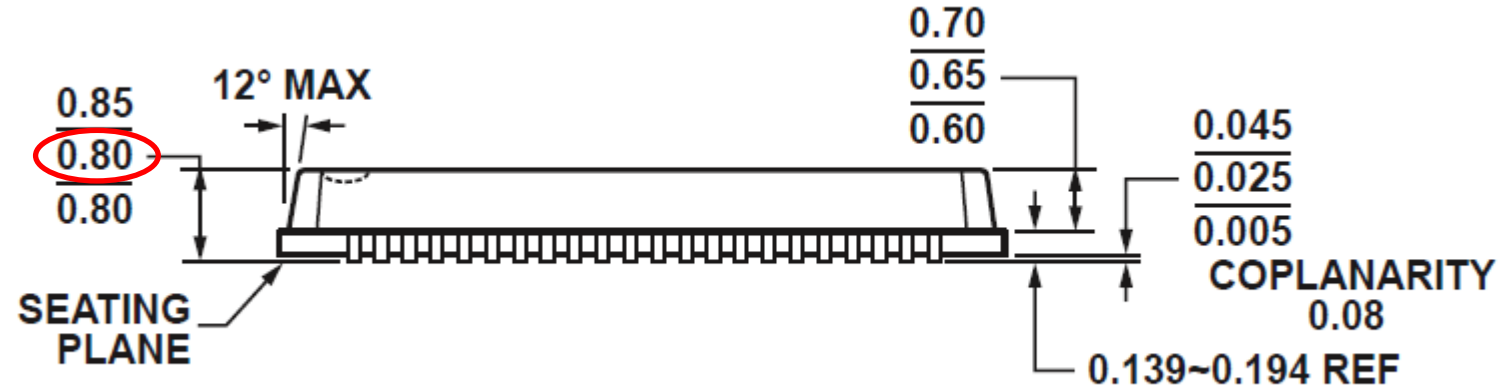
TED WEYGAN

Assembly Engineer

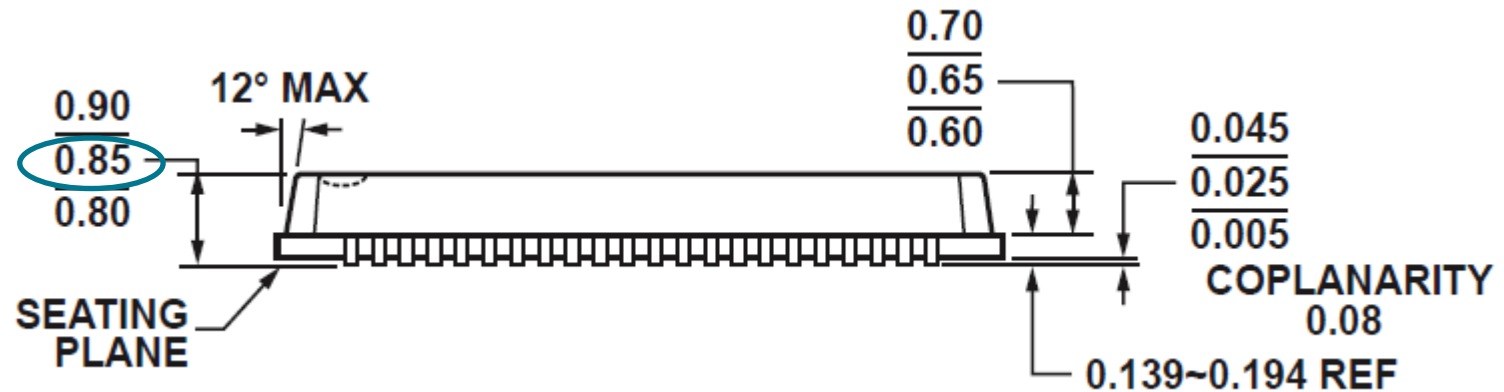


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FROM:

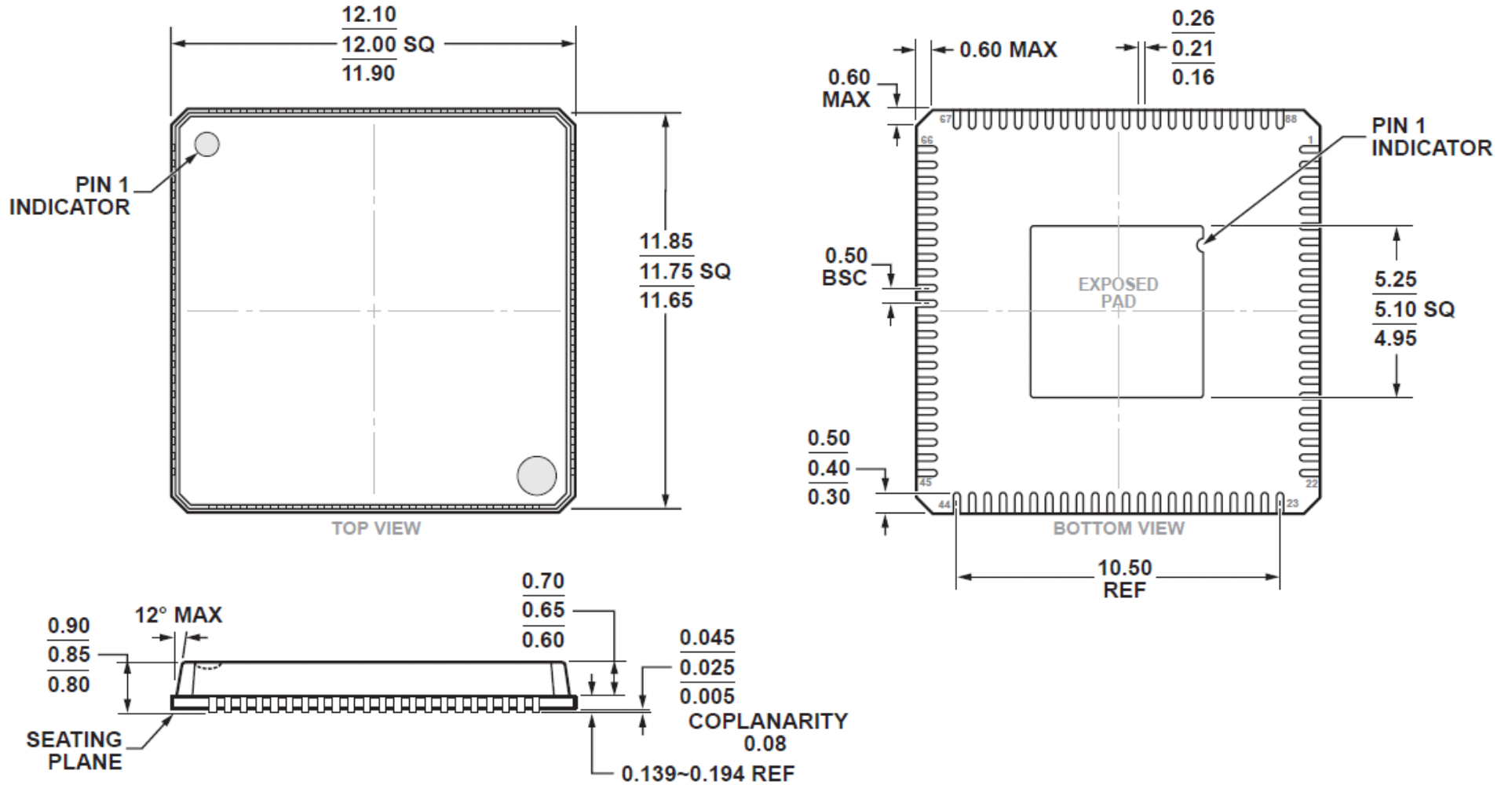


TO:



**88-Lead Lead Frame Chip Scale Package [LFCSP]
12 x 12 mm Body and 0.85 mm Package Height
(CP-88-7)**

Dimensions shown in millimeters



Qualification Results Summary for 12x12mm Punched LFCSP at STATS ChipPAC Singapore

QUALIFICATION PLAN			
TEST	SPECIFICATION	SAMPLE SIZE	RESULT
Temperature Cycle (TC)*	JEDEC <i>JESD22-A104</i>	9 x 49	Pass
Unbiased Highly Accelerated Stress Test (uHAST)*	JEDEC <i>JESD22-A118</i>	9 x 49	Pass
Highly Accelerated Stress Test (HAST)*	JEDEC <i>JESD22-A110</i>	9 x 49	Pass
Solder Heat Resistance (SHR)*	JEDEC/IPC <i>J-STD-020</i>	9 x 11	Pass
High Temperature Storage Life (HTSL)	JEDEC <i>JESD22-A103</i>	3 x 49	Pass

*Preconditioned per JEDEC/IPC J-STD-020